APPLICABLE STANDARD				
	Operating Temperature Range	−55 °C to +105 °C(1)	Storage Temperature Range	−10 °C to +60 °C(2)
Rating	Voltage	100 V AC	Storage Humidity Range	Relative humidity 85 % MAX (Not dewed)
	Current	0.5 A	Operating Humidity Range	

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
General Examination	Visually and by measuring instrument.	According to drawing.	×	×
Marking	Confirmed visually.		×	×
ELECTRIC CHARACTERISTICS				
Contact Resistance	100 mA(DC or 1000 Hz)	30 mΩ MAX (3)	×	—
Insulation Resistance	250 V DC	1000 MΩ MIN	×	—
Voltage Proof	300 V AC for 1 min.	No flashover or breakdown. △1	×	—
MECHANICAL CHARACTERISTICS				
Insertion and Withdrawal Forces	Measured by applicable connector.	Insertion Force: 26.7 N MAX Withdrawal Force: 2.7 N MIN	×	—
Mechanical Operation	100 times insertions and extractions.	1) Contact Resistance : 40 mΩ MAX (3) 2) No damage, crack and looseness of parts.	×	—
Vibration	Frequency 10 to 55 to 10 Hz, approx 5 min. Single amplitude: 0.75 mm, 10 cycles for 3 axial directions.	1) No electrical discontinuity of 1 μs. 2) No damage, crack and looseness of parts.	×	—
Shock	490 m/s^2, duration of pulse 11 ms at 3 times for 3 both axial directions.		×	—
ENVIRONMENTAL CHARACTERISTICS				
Damp Heat (Steady state)	Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.	1) Contact Resistance : 40 mΩ MAX (3) 2) Insulation Resistance: 1000 MΩ MIN 3) No damage, crack and looseness of parts.	×	—
Rapid Change of Temperature	Temperature: −55 → +85 °C Time : 30 → 30 min. Under 5 cycles. (Relocation time to chamber: within 2 to 3 MIN)		×	—
Dry Heat	Exposed at +105 °C, 96 h	1) Contact Resistance : 40 mΩ MAX (3) 2) No damage, crack and looseness of parts.	×	—
Cold	Exposed at −55 °C, 96 h		×	—
Resistance to Soldering Heat	1) Reflow soldering: Peak TMP: 260 °C MAX Reflow TMP: 220 °C MIN for 60 sec 2) Soldering irons: 360 °C MAX for 5 sec.	No deformation of case of excessive looseness of the terminal.	×	—
Solderability	Soldered at solder temperature 240 ± 3 °C for immersion duration, 3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	—

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△1	2	DIS-F-00003292	MT.ITANO	HT.YAMAGUCHI	18.04.16

REMARKS
(1) Include temperature rise caused by current-carrying.
(2) "Storage" means a long-term storage state for the unpacked part before assembly to pcb.
(3) Contact resistance of relay board is not included. It becomes contact resistance for 1 connector. △1
Unless otherwise specified, refer to IEC 60512.

APPROVED	NH.NAKATA	17.11.01
CHECKED	MK.NAGATA	17.10.31
DESIGNED	KJ.NISHIWAKI	17.10.31
DRAWN	KJ.NISHIWAKI	17.10.31

Note QT:Qualification Test AT:Assurance Test X:Applicable Test

DRAWING NO.		ELC-376551-00-00	
HRS	SPECIFICATION SHEET	PART NO.	FX27-40S-0.8SV
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL577-1002-0-00 △1 1/1

FORM HD0011-2-1